

150V,84A, 8.1mΩ N-channel Power SGT MOSFET

JMSH1509PC

Features

- $\bullet \;\;$ Excellent $R_{DS(ON)}$ and Low Gate Charge
- 100% UIS TESTED
- 100% ΔVds TESTED
- Halogen-free; RoHS-compliant
- Pb-free plating

Applications

- Load Switch
- PWM Application
- Power Management

Product Summary

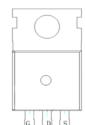
Parameters	Value	Unit
$V_{\rm DSS}$	150	٧
$V_{GS(th)_Typ}$	3.2	٧
$I_D(@V_{GS}=10V)$	84	Α
$R_{DS(ON)_Typ}(@V_{GS}=10V$	8.1	mΩ



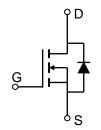








Pin Assignment



Schematic Diagram

Ordering Information

Device	Marking	MSL	Form	Package	Tube(pcs)	Per Carton (pcs)
JMSH1509PC	JMSH1509PC	N/A	Tube	TO-220-3L	50	5000

Absolute Maximum Ratings (@ T_C = 25°C unless otherwise specified)

Symbol	Parameter		Value	Unit	
V_{DS}	Drain-to-Source Voltage		150	V	
V_{GS}	Gate-to-Source Voltage		±20	V	
I-	Continuous Drain Current	$T_C = 25^{\circ}C$	84	А	
I _D	Continuous Diain Current	$T_C = 100$ °C	59		
I_{DM}	Pulsed Drain Current (1)	· •	Refer to Fig.4	Α	
E _{AS}	Single Pulsed Avalanche Energy (2)		536	mJ	
P_{D}	Power Dissipation	$T_C = 25^{\circ}C$	170	W	
ט י		$T_C = 100$ °C	68	VV	
T_{J} , T_{STG}	Junction & Storage Temperature R	Range	-55 to 150	°C	

Thermal Characteristics

Symbol	Parameter	Мах	Unit
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient ⁽³⁾	28	°C/W
$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.7	C/VV



Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Off Cha	aracteristics					
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	150	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 120V, V_{GS} = 0V$	-	-	1.0	μА
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Cha	racteristics	•				
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.2	3.2	4.1	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽⁴⁾	$V_{GS} = 10V, I_D = 20A$	-	8.1	10.6	mΩ
Dynami	ic Characteristics					
R_g	Gate Resistance	f = 1MHz	-	3.7	-	Ω
C _{iss}	Input Capacitance	V 2V V -=V	-	3569	-	pF
C _{oss}	Output Capacitance	$V_{GS} = 0V, V_{DS} = 75V,$ f = 1MHz	-	323	-	pF
C_{rss}	Reverse Transfer Capacitance	- 1- 11/11/2	-	14	-	pF
Q_g	Total Gate Charge		-	53	-	nC
Q_{gs}	Gate Source Charge	$V_{GS} = 0 \text{ to } 10V$ $V_{DS} = 75V, I_{D} = 20A$	-	19	-	nC
Q_{gd}	Gate Drain("Miller") Charge	V _{DS} = 73V, I _D = 20A	-	12	-	nC
Switchi	ing Characteristics					
t _{d(on)}	Turn-On DelayTime		-	16	-	ns
t _r	Turn-On Rise Time	$V_{GS} = 10V, V_{DD} = 75V$	-	29	-	ns
t _{d(off)}	Turn-Off DelayTime	$I_D=20A$, $R_{GEN}=3\Omega$	-	39	-	ns
t _f	Turn-Off Fall Time	1	-	16	-	ns
Body D	iode Characteristics					
I _S	Maximum Continuous Body Diode Forward Current		-	-	84	Α
I _{SM}	Maximum Pulsed Body Diode Forward Current		-	-	336	Α
V _{SD}	Body Diode Forward Voltage	$V_{GS} = 0V, I_{S} = 30A$	-		1.2	V
trr	Body Diode Reverse Recovery Time	1 454 4:/-1: 4004/ -	-	85	-	ns
Qrr	Body Diode Reverse Recovery Charge	$I_F = 15A$, di/dt = 100A/us	-	253	-	nC

Notes:

^{1.} Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

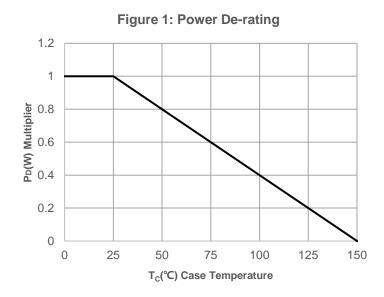
 $^{2.~}E_{AS}~condition:~Starting~T_J=25C,~V_{DD}=75V,~V_G=10V,~R_G=25ohm,~L=3mH,~I_{AS}=18.9A,~V_{DD}=0V~during~time~in~avalanche.$

^{3.} R_{BJA} is measured with the device mounted on a 1inch² pad of 2oz copper FR4 PCB.

^{4.} Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 0.5%.



Typical Performance Characteristics



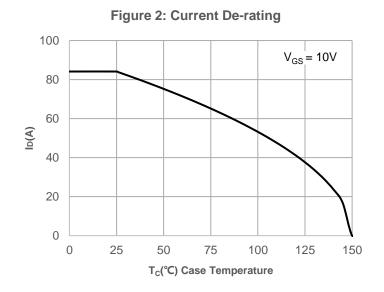
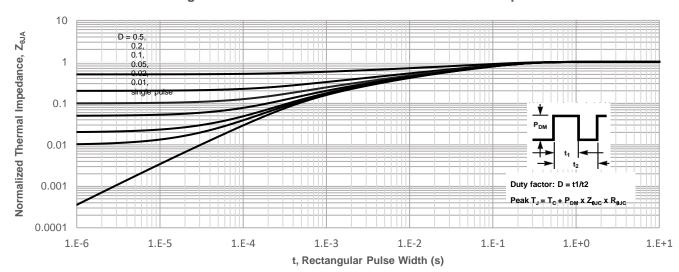
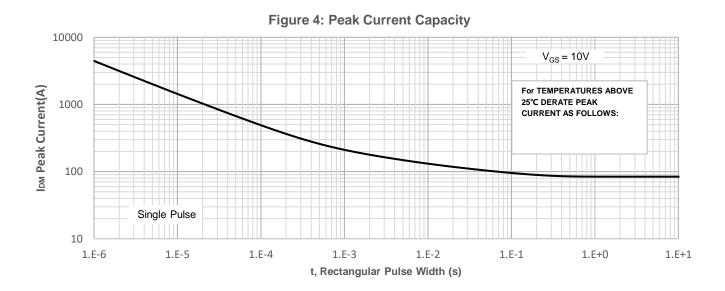


Figure 3: Normalized Maximum Transient Thermal Impedance







Typical Performance Characteristics

Figure 5: Output Characteristics

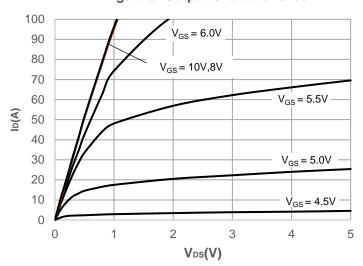


Figure 6: Typical Transfer Characteristics

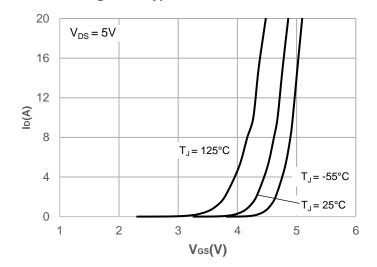


Figure 7: On-resistance vs. Drain Current

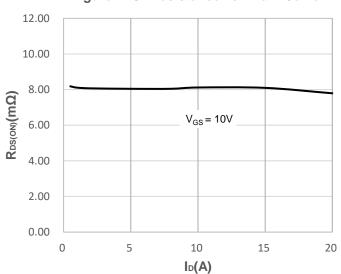


Figure 8: Body Diode Characteristics

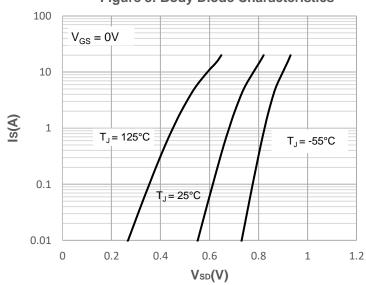


Figure 9: Gate Charge Characteristics

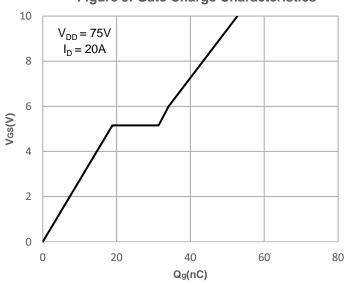
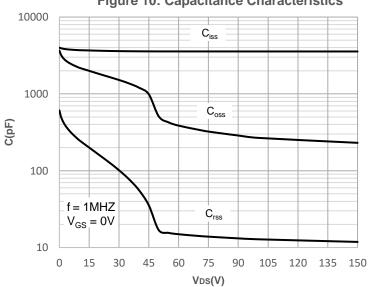


Figure 10: Capacitance Characteristics





Typical Performance Characteristics

Figure 11: Normalized Breakdown voltage vs. Junction Temperature

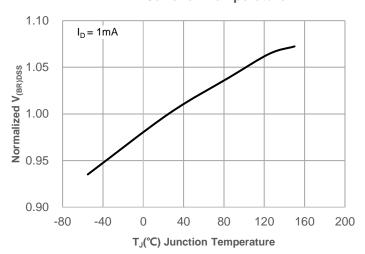


Figure 13: Normalized Threshold Voltage vs. Junction Temperature

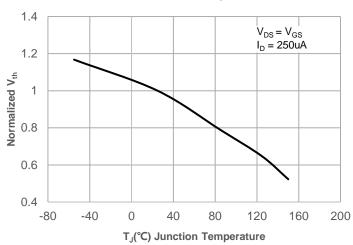


Figure 15: Maximum Safe Operating Area

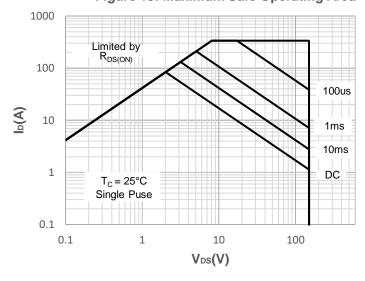
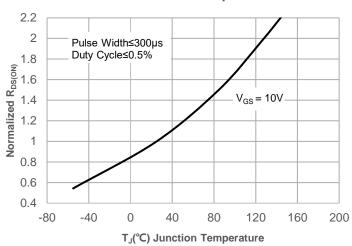
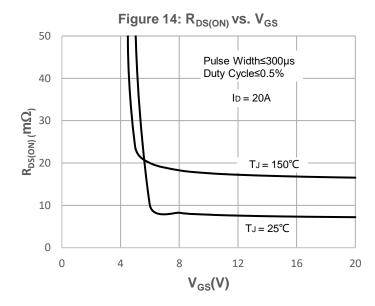


Figure 12: Normalized on Resistance vs.
Junction Temperature







Test Circuit

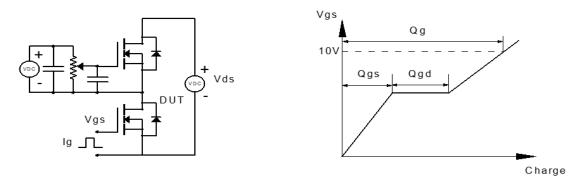


Figure 1: Gate Charge Test Circuit & Waveform

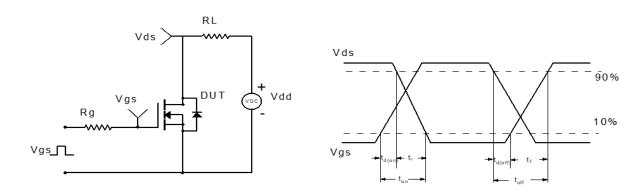


Figure 2: Resistive Switching Test Circuit & Waveform

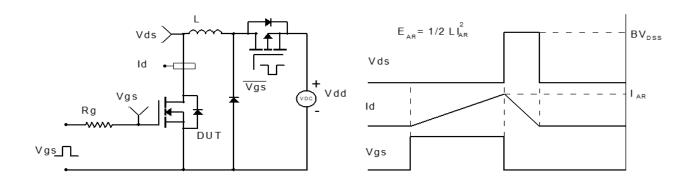


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

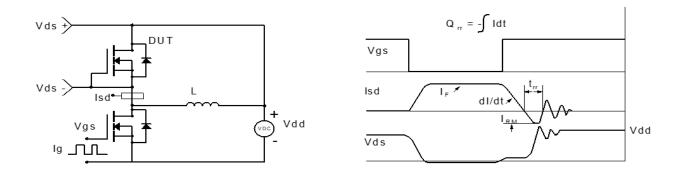
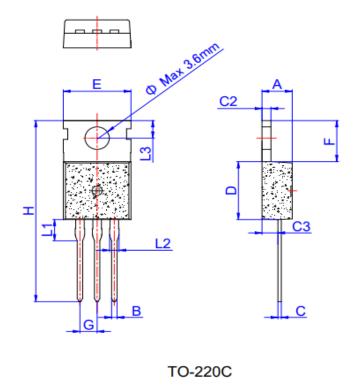


Figure 4: Diode Recovery Test Circuit & Waveform



Package Mechanical Data(TO-220-3L)



			Dime	ensions		
Ref.	Millimeters			Inches		
	Min.	Тур.	Max.	Min.	Тур.	Max.
Α	4.40		4.60	0.173		0.181
В	0.70		0.90	0.028		0.035
С	0.45		0.60	0.018		0.024
C2	1.23		1.32	0.048		0.052
C3	2.20		2.60	0.087		0.102
D	8.90		9.90	0.350		0.390
E	9.90		10.3	0.390		0.406
F	6.30		6.90	0.248		0.272
G		2.54			0.1	
Н	28.0		29.8	1.102		1.173
L1		3.39			0.133	
L2	1.14		1.70	0.045		0.067
L3	2.65		2.95	0.104		0.116
Φ		3.6			0.142	

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